

ABS

ROHS
COMPLIANT

Pb
Pb-Free

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

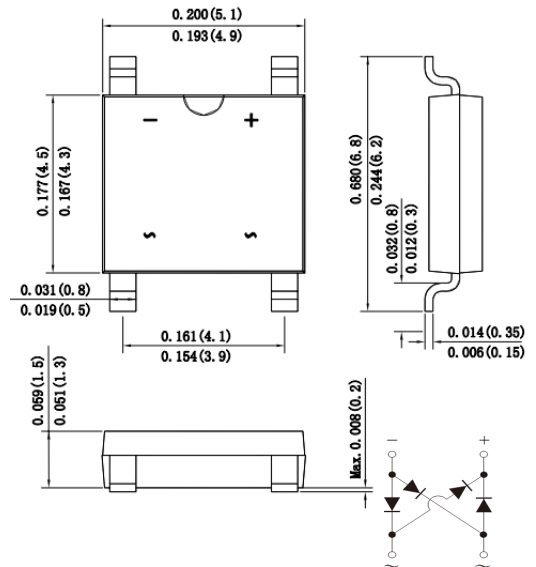
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0034 ounce, 0.098 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ABS205	ABS21	ABS22	ABS24	ABS26	ABS28	ABS210	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	60.0							A
Rating for fusing ($t=8.3\text{ms}$, $T_a=25^\circ\text{C}$)	I_t^2	14.9							A^2s
Maximum instantaneous forward voltage at 2.0A	V_F	1.0							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	2.0 200							μA
Typical junction capacitance (Note 2)	C_J	23.0							pF
Typical thermal resistance	$R_{\theta JA}$	75.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3*1.3mm solder pad
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

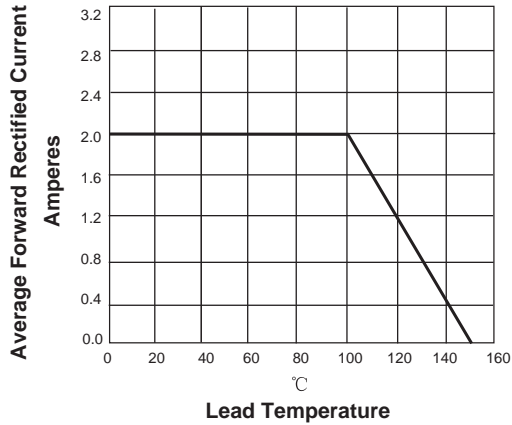


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

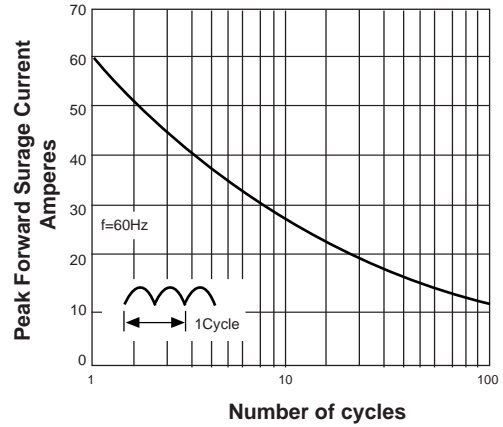


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

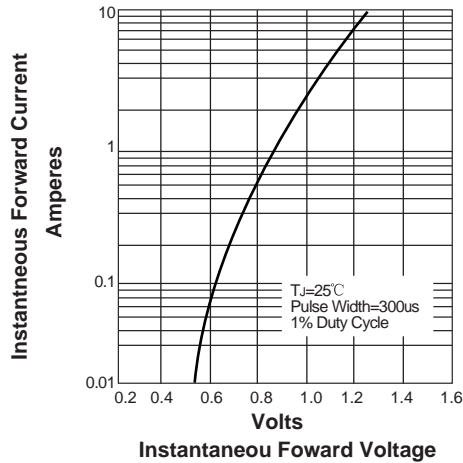
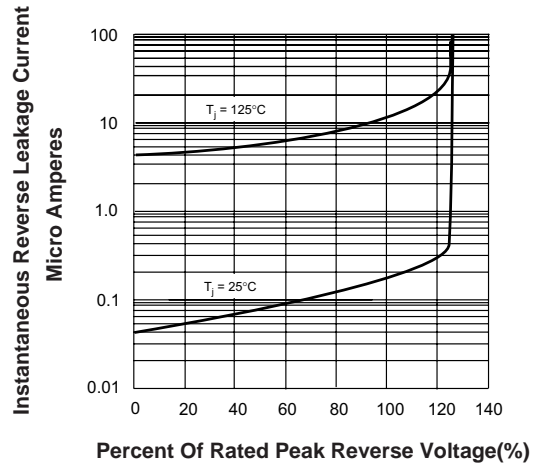
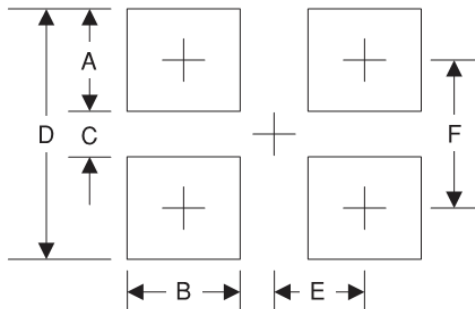


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

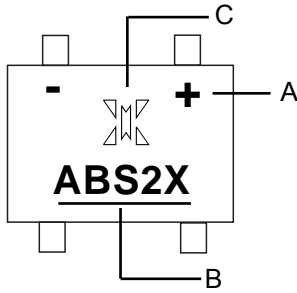


Suggested Pad Layout



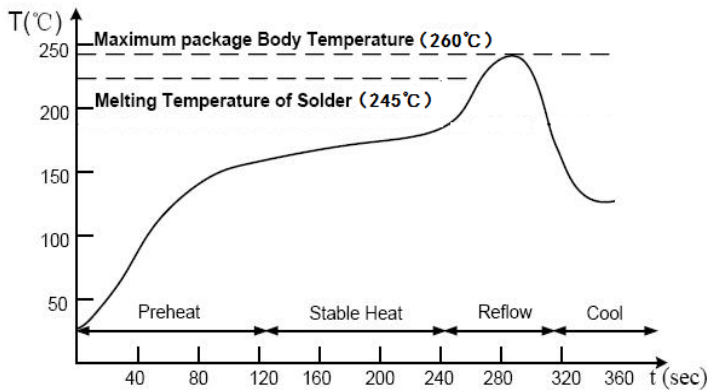
Symbol	Unit (mm)	Unit (inch)
A	1.5	0.059
B	1.0	0.039
C	4.22	0.166
D	7.22	0.284
E	2.0	0.078
F	5.70	0.224

Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name,X : 05.1.....10
C	Logo

Suggested Soldering Temperature Profile

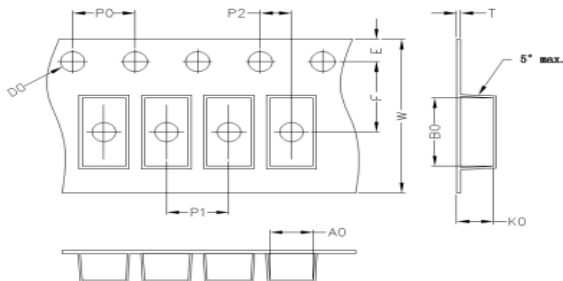


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.31	6.68	1.6	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
ABS	11'	278	3	280	6	355*310*310	48
	13'	330	5	338	10	365*365*360	80